



Process Change Notification

May-21-2019

Title: MCC Introduces new lead frame for TO-277 package

PCN#: 052119-1

Planned Effective Date Code :1936

Reliability Data: Available per individual request

Samples contact: Sales@mccsemi.com

For question concerning this notification: techsupport@mccsemi.com

Notification Type:

Final Process/Product Change Notification(FPCN)

MCC will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact techsupport@mccsemi.com

Description and purpose :

Devices with new process: automatic assembly to ensure more stable quality, larger pad size, expand product series. Internal qualification process had been finished and the report is available by individual request.

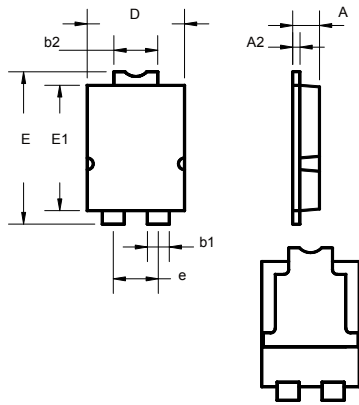
For any concern about this PCN, please feel free to contact your local sales representative or us directly via above E-mail address.

Qualification Test Result:

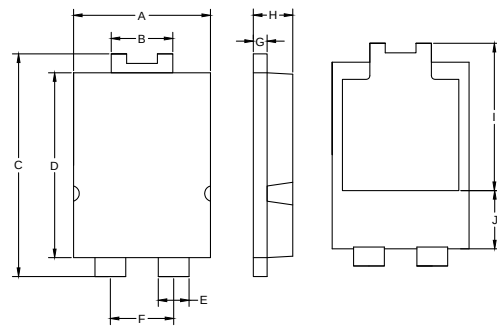
Test	Condition	Interval	Results
HTRB	Tj=150℃, 80% Vr,	1000 Hrs	0/77
OP	Ta=25℃, Rated If,	1000 Hrs	0/77
PCT	Ta=121℃, 100%RH, 15psig	96 Hrs	0/77
TC	-55℃~+150℃	1000 Cycles	0/77
Resistance to solder heat	260℃ for 10s		0/10
Solderability	245℃ for 5s		0/10

Comparison between Before Change and After Change part appearance

Before Change



After Change



DIMENSIONS					
DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.041	0.045	1.05	1.15	
A2	0.010	0.014	0.25	0.35	
b1	0.031	0.039	0.80	1.00	
b2	0.067	0.075	1.70	1.90	
D	0.154	0.161	3.90	4.10	
E	0.252	0.260	6.40	6.60	
E1	0.205	0.215	5.20	5.40	
e	0.071	0.075	1.80	1.90	

DIMENSIONS					
DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.154	0.161	3.90	4.10	
B	0.067	0.075	1.70	1.90	
C	0.252	0.260	6.40	6.60	
D	0.209	0.217	5.30	5.50	
E	0.031	0.039	0.80	1.00	
F	0.071	0.075	1.80	1.90	
G	0.014	0.018	0.35	0.45	
H	0.043	0.047	1.10	1.20	
I	0.161	0.177	4.10	4.50	
J	0.059	0.075	1.50	1.90	

Affected Pn#:

MBR10U45L-TP
MBR10U60-TP
MBR12U100L-TP
MBR15U100-TP
MBR15U45-TP
MBR15U60-TP